

ABSTRACT OF THE DISCLOSURE

A member for a circuit board according to the present invention includes a prepreg and a mold release film that is provided on at least one side of the prepreg. The mold release film contains or is coated with a heat absorbing substance having a heat absorbing property. A method of manufacturing a member for a circuit board according to the present invention includes allowing a mold release film to adhere to at least one side of a prepreg by heating and pressing. The mold release film contains or is coated with a heat absorbing substance having a heat absorbing property. In the method, the heating is performed at a temperature not lower than a softening point of the prepreg and not higher than an endothermic temperature of the heat absorbing substance. Thus, a member for a circuit board that can prevent or reduce the occurrence of deformation such as contraction of a mold release film even when processing holes using a laser or the like, a method of manufacturing the same, and methods of manufacturing circuit boards are provided.